○ Emerging materials
○ Heterogeneous integration, chip stacking, and related technologies.
○ High-density substrates
○ Metrology
○ Modeling and simulation
○ Package-level design/codesign tools for electrical, thermal and mechanical design of complex packages
○ Printed circuit boards
○ Safety and security
○ Software, firmware, new concepts in programming
○ Standards
○ Test solutions to assure yield in complex packages
○ Thermal solutions
○ Tooling
○ Other?

3. A proposed National Advanced Packaging Manufacturing Program could be oriented to address multiple needs, including but not limited to prototyping, the provision of pilot lines, work force development, and supply chain development. Please describe the most critical needs on which the program should focus.

4. What attributes are the most important for a National Advanced Packaging Manufacturing Program to deliver? Examples include but are not limited to:

○ ''Leading edge'' tools
○ Characterization services
○ Collaboration across multiple universities and multiple companies
○ Development of education and workforce development infrastructure, including building a pipeline of skilled workers
○ Easy to access facility, with different processes and tools
○ Expert resident staff for custom development
○ International participation
○ Intellectual property protection for inventors
○ Open access to intellectual property
○ Post fabrication infrastructure
○ Other?

5. What factors are critical to enable a National Advanced Packaging Manufacturing Program to provide a successful packaging R&D hub(s)?

6. Identify processes, equipment, measurement capabilities, environmental conditions, and training facilities that are most crucial for facilities provided by a National Advanced Packaging Manufacturing Program. How might organizations access such facilities?

7. How closely aligned should the capabilities enabled by a National Advanced Packaging Manufacturing Program be with those provided by the NSTC?

8. How should the National Advanced Packaging Manufacturing Program connect to National Network for Semiconductor R&D, authorized by Sec. 9903 of the FY 2021 NDAA? What considerations should be given to ensure strong integration between the two efforts? Should there be overlap in the technology readiness levels served by each program?

9. Describe anticipated needs in education and workforce development, including retraining and upskilling, in the semiconductor packaging area. How adequate is it currently, and what are future expectations of need? How should the workforce training pipeline be developed?

Semiconductor Workforce

1. What are the greatest occupational or skills shortages facing employers in the semiconductor sector? What are the consequences of those shortages with respect to the domestic operation of employers in the sector? Considering all aspects of building, equipping, and running semiconductor manufacturing and R&D facilities, what actions have been taken to address these shortages, how effective have they been, and what gaps remain?

2. What strategies have been most effective in addressing the shortages? Which states or countries have created the most effective strategies for different types of workforce needs to build, equip, and run semiconductor manufacturing and R&D facilities?

What industry or other credentials do employers use, or could use, to train and hire workers to fill needed positions? To what extent do employers in the semiconductor sector partner with government institutions such as local workforce boards, economic development organizations, or Manufacturing Extension Partnership centers, or international partners to establish training and/or skill certification programs? To what extent do employers in the semiconductor sector partner with other employers to create joint training programs?

3. What types of apprenticeship programs or existing partnerships involving workforce development issues in the semiconductor sector should the Department be aware of? What role can unionized labor play in worker training and workforce development, including for economically disadvantaged individuals?

4. What have been successful mechanisms used by employers in the semiconductor sector to work with local high schools, career and technical education programs, community

colleges, or universities to recruit and train workers?

5. Are there any current or planned initiatives in the semiconductor sector to strengthen and expand the recruitment of women and underrepresented minorities, including promotion of such careers at K–12 levels?

6. To what extent, and for what occupations, do organizations in the semiconductor sector use the H1–B Program to fill positions?

7. Are there opportunities to design the semiconductor incentive program to ensure that worker skills shortages do not hinder companies from expanding operations?

Sreenivas Ramaswamy,

Senior Policy Advisor, Office of Policy and Strategic Planning, U.S. Department of Commerce.

[FR Doc. 2022–01305 Filed 1–21–22; 8:45 am]

BILLING CODE 3510–20–P

DEPARTMENT OF COMMERCE

National Institute of Standards and Technology (NIST)

Information Collection Activities; Submission to the Office of Management and Budget (OMB) for Review and Approval; Comment Request; Baldrige Executive Fellows Program

The Department of Commerce will submit the following information collection request to the Office of Management and Budget (OMB) for review and clearance in accordance with the Paperwork Reduction Act of 1995, on or after the date of publication of this notice. We invite the general public and other Federal agencies to comment on proposed, and continuing information collections, which helps us assess the impact of our information collection requirements and minimize the public's reporting burden. Public comments were previously requested via the **Federal Register** on November 16, 2021, during a 60-day comment period. This notice allows for an additional 30 days for public comments.

Agency: National Institute of Standards and Technology (NIST), Commerce.

Title: Baldrige Executive Fellows Program.

OMB Control Number: 0693–0076.

Form Number(s): None.

Type of Request: Regular, extension of current information collection.

Number of Respondents: 24 per year.

Average Hours per Response: 1 hour to gather materials.

Burden Hours: 24.

Needs and Uses: Collection needed to obtain information to select applicants for the Baldrige Executive Fellows Program, a professional development fellowship offered by the Baldrige Performance Excellence Program.

Affected Public: Business, health care, education, or other for-profit organizations; health care, education, and other non-profit organizations; and individuals.

Frequency: Annually.

Respondent's Obligation: Voluntary.

This information collection request may be viewed at *www.reginfo.gov.* Follow the instructions to view the Department of Commerce collections currently under review by OMB.

Written comments and recommendations for the proposed information collection should be submitted within 30 days of the publication of this notice on the following website *www.reginfo.gov/ public/do/PRAMain.* Find this particular information collection by selecting ''Currently under 30-day Review—Open for Public Comments'' or by using the search function and entering either the title of the collection or the OMB Control Number 0693–0076.

Sheleen Dumas,

Department PRA Clearance Officer, Office of the Chief Information Officer, Commerce Department.

[FR Doc. 2022–01265 Filed 1–21–22; 8:45 am]

BILLING CODE 3510–13–P

DEPARTMENT OF COMMERCE

National Institute of Standards and Technology

[Docket No. 211115–0232]

Announcing Issuance of Federal Information Processing Standard (FIPS) 201–3, Personal Identity Verification (PIV) of Federal Employees and Contractors

AGENCY: National Institute of Standards and Technology (NIST), Commerce.

ACTION: Notice.

SUMMARY: This notice announces the Secretary of Commerce's approval of Federal Information Processing Standard (FIPS) Publication 201–3, Personal Identity Verification (PIV) of Federal Employees and Contractors. FIPS 201–3 includes clarifications to existing text, additional text in cases where there were ambiguities, adaptation to changes in the environment since the publication of FIPS 201–2, and specific changes

requested by Federal agencies and implementers.

DATES: FIPS 201–3 is effective on January 24, 2022.

ADDRESSES: FIPS 201–3 is available electronically from the NIST website at: *https://csrc.nist.gov/publications/fips.* Comments that were received on the proposed changes will also be published electronically at *https://csrc.nist.gov/ projects/piv* and at https:// www.regulations.gov.

FOR FURTHER INFORMATION CONTACT: Hildegard Ferraiolo, (301) 975–6972, National Institute of Standards and Technology, 100 Bureau Drive, Mail Stop 8930, Gaithersburg, MD 20899– 8930, email: *hildegard.ferraiolo@ nist.gov,* or Andrew Regenscheid, (301) 975–5155, *andrew.regenscheid@ nist.gov.*

SUPPLEMENTARY INFORMATION: FIPS 201 establishes a standard for a Personal Identity Verification (PIV) system (Standard) that meets the control and security objectives of Homeland Security Presidential Directive-12 (HSPD–12). It is based on secure and reliable forms of identity credentials issued by the Federal Government to its employees and contractors. These credentials are used by mechanisms that authenticate individuals who require access to federally controlled facilities, information systems, and applications. This Standard addresses requirements for initial identity proofing, infrastructure to support interoperability of identity credentials, and accreditation of organizations issuing PIV credentials.

FIPS 201 was issued on 2005 (70 FR 17975) in response to HSPD–12. Subsequent revisions included FIPS 201–1, published in 2006 and FIPS 201– 2 (version in effect), published in 2013 (78 FR 54626). In consideration of technological advancements over the last five years and specific requests for changes from United States Government (USG) stakeholders, NIST determined that a third revision of FIPS 201 was warranted. NIST received numerous change requests, some of which, after analysis and coordination with the Office of Management and Budget (OMB) and USG stakeholders, were incorporated in a proposed draft of FIPS 201–3. Other change requests incorporated in the draft resulted from the 2019 Business Requirements Meeting held at NIST. The meeting focused on business requirements of Federal departments and agencies. On November 3, 2020, a notice was published in the **Federal Register** (85 FR 69599), soliciting public comments

on the draft FIPS 201–3. During the public comment period, a virtual public workshop was hosted by NIST on December 9, 2020.

The scope of changes reflected in FIPS 201–3 include the following:

• Alignment with current NIST technical guidelines on identity management, OMB policy guidelines, and changes in commercially-available technologies and services.

• Accommodation of additional types of authenticators through an expanded definition of Derived PIV credentials.

• Focus on the use of federation to facilitate interoperability and interagency trust.

• Addition of supervised remote identity proofing processes.

• Removal of previously deprecated Cardholder Unique Identifier (CHUID) authentication mechanism and deprecation of the symmetric card authentication key and visual authentication mechanisms (VIS).

• Support for secure messaging authentication mechanism (SM–AUTH).

Comments and questions regarding the draft were submitted by USG organizations, private sector organizations, and private individuals. NIST made several changes to the draft FIPS 201–3 based on the public comments received.

Many commenters asked for clarification of the text of the Standard and/or recommended editorial and/or formatting changes. Other commenters suggested modifying the requirements and asked questions concerning the implementation of the Standard. All of the suggestions, questions, and recommendations within the scope of this FIPS were carefully reviewed, and changes were made to the Standard, where appropriate. Some commenters submitted questions or raised issues that were related but outside the scope of this FIPS. Comments that were outside the scope of this FIPS, but that were within the scope of one of the related Special Publications, were deferred for later consideration in the context of the revisions to these Special Publications. The disposition of each comment that was received has been provided along with the comments at *https:// csrc.nist.gov.*

The following is a summary and analysis of the comments received during the public comment period, and NIST's responses to them:

1. Comment: Some commenters inquired about the effective date of the Standard. Commenters also inquired about the implementation schedule associated with the changes introduced in the Standard, once the Standard is in effect.